

*IGBT* 

# SGW23N60UF

# **Ultra-Fast IGBT**

# **General Description**

Fairchild's UF series of Insulated Gate Bipolar Transistors (IGBTs) provides low conduction and switching losses. The UF series is designed for applications such as motor control and general inverters where high speed switching is a required feature.

### **Features**

- · High speed switching
- Low saturation voltage :  $V_{CE(sat)} = 2.1 \text{ V } @ I_C = 12 \text{A}$
- · High input impedance

# **Applications**

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Description		SGW23N60UF	Units
V <sub>CES</sub>	Collector-Emitter Voltage		600	V
V <sub>GES</sub>	Gate-Emitter Voltage		± 20	V
	Collector Current	@ $T_C = 25^{\circ}C$	23	А
lc	Collector Current	@ T <sub>C</sub> = 100°C	12	А
I <sub>CM (1)</sub>	Pulsed Collector Current		92	А
P <sub>D</sub>	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	100	W
	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	40	W
TJ	Operating Junction Temperature		-55 to +150	°C
T <sub>stg</sub>	Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds		300	°C

#### Notes :

(1) Repetitive rating : Pulse width limited by max. junction temperature

# **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.2	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (PCB Mount) (2)		40	°C/W

#### Notes

(2) Mounted on 1" squre PCB (FR4 or G-10 Material)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chai	racteristics					
BV <sub>CES</sub>	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	600			V
ΔB <sub>VCES</sub> / ΔΤ <sub>J</sub>	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V, I_{C} = 1mA$		0.6		V/°C
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			250	uA
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Char	acteristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	$I_C = 12mA$ , $V_{CE} = V_{GE}$	3.5	4.5	6.5	V
	Collector to Emitter	$I_C = 12A$ , $V_{GE} = 15V$		2.1	2.6	V
$V_{CE(sat)}$	Saturation Voltage	$I_C = 23A$ , $V_{GE} = 15V$		2.6		V
	Characteristics					
C <sub>ies</sub>	Input Capacitance	$V_{CE} = 30V_{V_{GE}} = 0V_{V_{CE}}$		720		pF
C <sub>oes</sub>	Output Capacitance	- f = 1MHz		100		pF
C <sub>res</sub>	Reverse Transfer Capacitance	1 – 111112		25		pF
Switchir	ng Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time			17		ns
t <sub>r</sub>	Rise Time			27		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 12\text{A},$		60	130	ns
t <sub>f</sub>	Fall Time	$R_G = 23\Omega, V_{GE} = 15V,$		70	150	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 25°C		115		uJ
E <sub>off</sub>	Turn-Off Switching Loss			135		uJ
E <sub>ts</sub>	Total Switching Loss			250	400	uJ
t <sub>d(on)</sub>	Turn-On Delay Time			23		ns
t <sub>r</sub>	Rise Time			32		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 12\text{A},$		100	200	ns
t <sub>f</sub>	Fall Time	$R_G = 23\Omega, V_{GE} = 15V,$		220	250	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 125°C		205		uJ
E <sub>off</sub>	Turn-Off Switching Loss			320		uJ
E <sub>ts</sub>	Total Switching Loss			525	800	uJ
$Q_g$	Total Gate Charge	V <sub>CE</sub> = 300 V, I <sub>C</sub> = 12A,		49	80	nC
$Q_{ge}$	Gate-Emitter Charge	$V_{CE} = 300 \text{ V}, I_{C} = 12\text{A},$ - $V_{GF} = 15\text{V}$		11	17	nC
$Q_{gc}$	Gate-Collector Charge	VGE - 10 V		14	22	nC
L <sub>e</sub>	Internal Emitter Inductance	Measured 5mm from PKG		7.5		nΗ

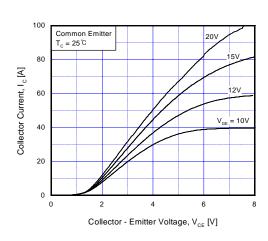


Fig 1. Typical Output Characteristics

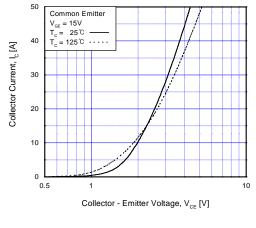


Fig 2. Typical Saturation Voltage Characteristics

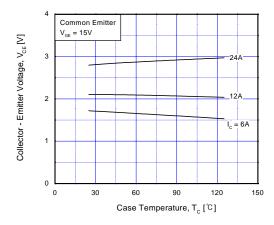


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

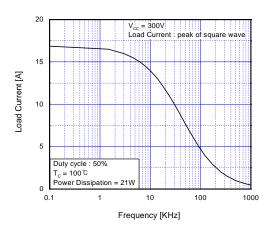


Fig 4. Load Current vs. Frequency

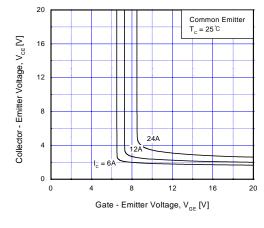


Fig 5. Saturation Voltage vs.  $V_{GE}$ 

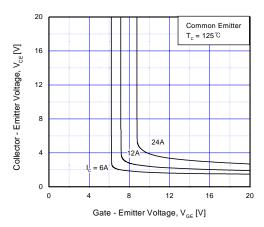
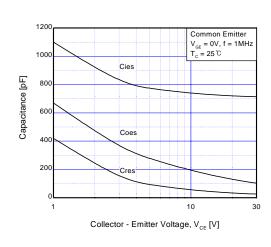


Fig 6. Saturation Voltage vs.  $V_{\rm GE}$ 

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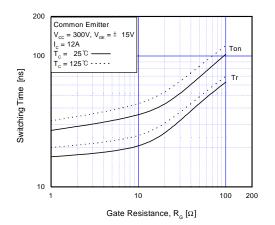
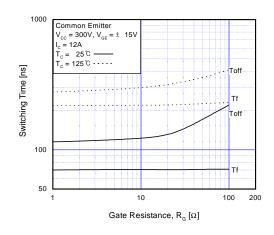


Fig 7. Capacitance Characteristics

Fig 8. Turn-On Characteristics vs.
Gate Resistance



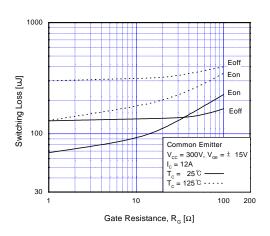
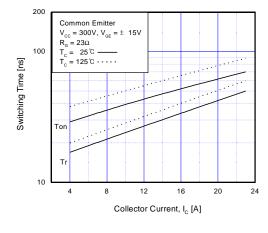


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance



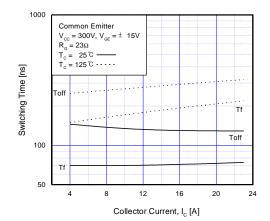
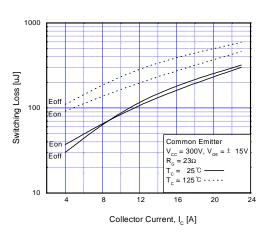


Fig 11. Turn-On Characteristics vs. Collector Current

Fig 12. Turn-Off Characteristics vs. Collector Current



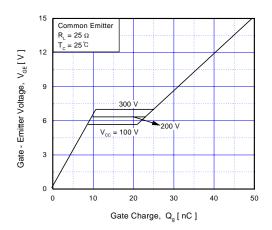
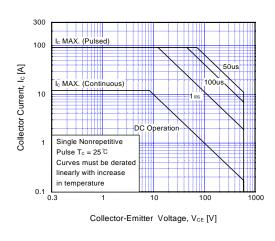


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



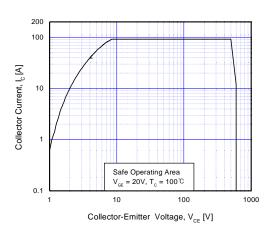


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA Characteristics

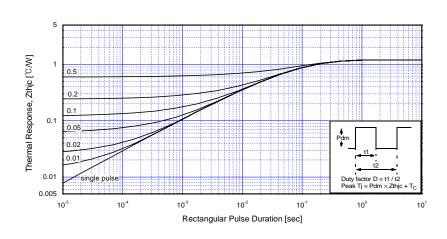
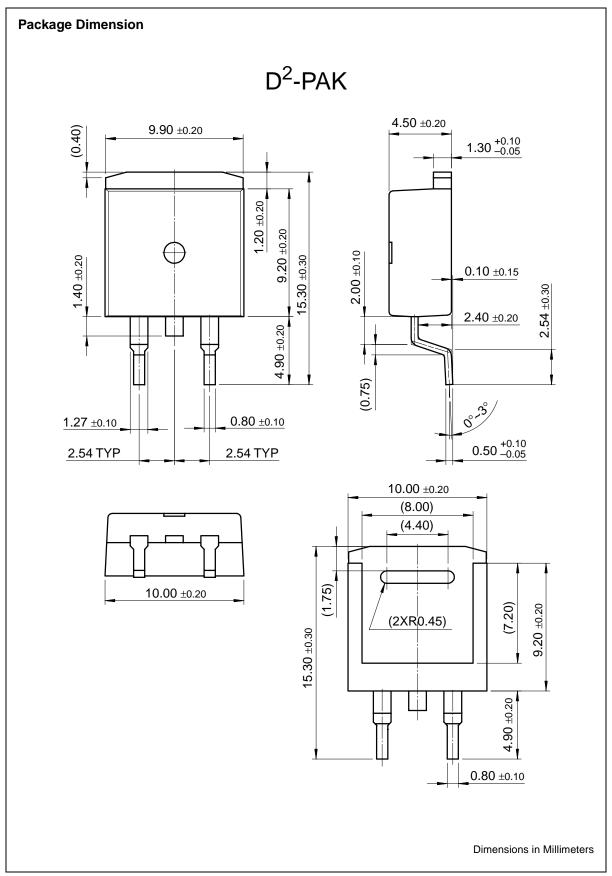


Fig 17. Transient Thermal Impedance of IGBT



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